# N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}$ (m $\Omega$ ) (Typ.)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
30	3.2 at V <sub>GS</sub> = 10 V	0.5	33.9 nC			
	6.2 at V <sub>GS</sub> = 4.5 V	85				

#### **FEATURES**

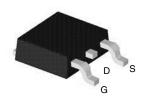
- DT-Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



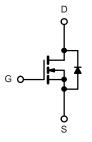
#### **APPLICATIONS**

DC/DC Converters

#### TO-252 Pin Configuration



Top View



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V <sub>DS</sub>	30				
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
Continuous Dusin Comment /T 450 °C\2	T <sub>C</sub> = 25 °C		85			
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>C</sub> = 100 °C	I <sub>D</sub>	64	Α		
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	255				
Single Avalanche Energy	E <sub>AS</sub>	380	mJ			
Maximum Power Dissipation <sup>c</sup>	T <sub>C</sub> = 25 °C	В	105	W		
Maximum Fower Dissipation	T <sub>C</sub> = 100 °C	$ P_D$	42	VV		
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	- 55 to +150	°C			

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	MAX	UNIT		
Junction-to-Ambient (PCB Mount) <sup>d</sup>	R <sub>thJA</sub>	65	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	1.2			

#### Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of R<sub>8JA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper,in a still air environment with Ta=25 °C.

Rev. 1. 0



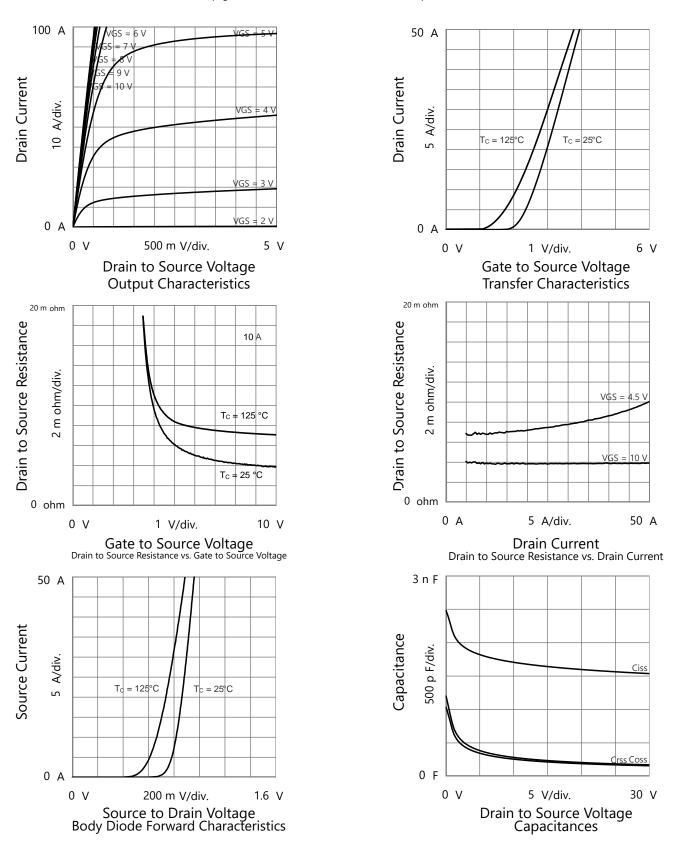
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0, I_D = 250 \mu A$	30			V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1		3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	1 20 μΑ	
Zero Gate voltage Drain Current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			20		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	85			Α	
Davis Course On Otata Basistana	P	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		3.2	5.5	mΩ	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A		6.2	8.9		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 5 \text{ V,I}_{D} = 20 \text{ A}$		30		S	
Dynamic <sup>b</sup>						1	
Input Capacitance	C <sub>iss</sub>	I		1640		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		235			
Reverse Transfer Capacitance	C <sub>rss</sub>	1		215			
Total Gate Charge	Qg			33.9		nC	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		2.99			
Gate-Drain Charge	Q <sub>gd</sub>	1		6.66			
Gate Resistance	R <sub>q</sub>	f = 1 MHz		2.6		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			13			
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, I_D = 20 \text{ A}, R_q = 3\Omega$		16			
Turn-Off DelayTime	t <sub>d(off)</sub>	V <sub>GS</sub> = 10 V		20		- ns	
Fall Time	t <sub>f</sub>	1		8			
<b>Drain-Source Body Diode Characterist</b>	ics						
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			85	А	
Pulse Diode Forward Current	I <sub>SM</sub>				255	_ ^	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 1 A		0.7	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 10 A, dl/dt = 100 A/µs, T <sub>.I</sub> = 25 °C		21		ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1- 10 Λ, αναι = 100 Λγμο, 1 J = 20 °C		23		nC	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

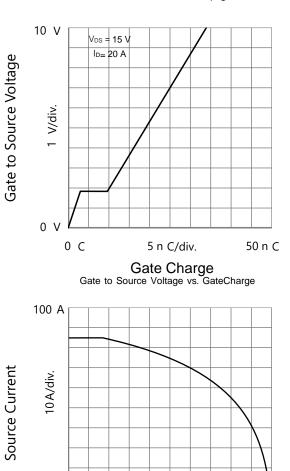
#### **TYPICAL CHARACTERISTICS** (T<sub>C</sub> = 25 °C, unless otherwise noted)



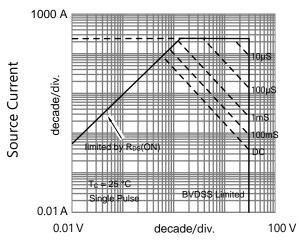


0 A

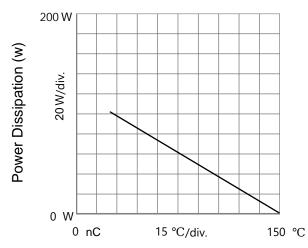
## **TYPICAL CHARACTERISTICS** ( $T_C = 25$ °C, unless otherwise noted)





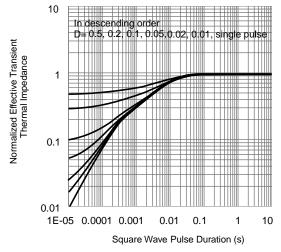


Source to Drain Voltage Safe Operating Area, Junction-to-Ambient



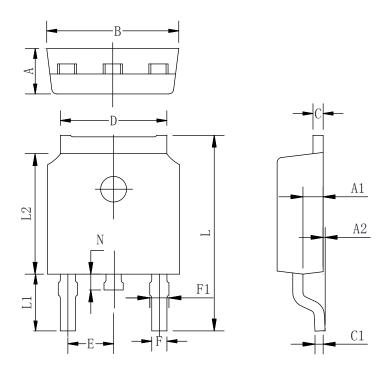
T<sub>C</sub> - Case Temperature

Current Derating



**Normalized Thermal Transient Impedance** 

# **TO-252-2L PACKAGE OUTLINE**



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max
A	2.10	2.30	2.50
A1	0.88	1.01	1.16
A2	0.00	0.15	0.28
В	6.40	6.60	6.80
С	0.42	0.50	0.63
C1	0.42	0.50	0.63
D	5.08	5.32	5.65
Е		2.286 TYP	
F	0.63	0.76	0.89
F1	0.64	0.86	1.08
L	9.30	9.90	10.80
L1	2.4	2.8	3.6
L2	5.90	6.10	6.55
N	0.57	0.80	1.05

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